



Material Content Data Sheet



Sales Product Name		IPD80R2K0P7		Issued		23. January 2018		
MA#		MA002116580						
Package		PG-TO252-3-342		Weight*		333.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.085	0.33	0.33	3257	3257
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		144	
	non noble metal	iron	7439-89-6	0.160	0.05		481	
	non noble metal	copper	7440-50-8	160.096	48.04	48.10	480392	481017
	non noble metal	aluminium	7429-90-5	0.139	0.04	0.04	418	418
wire	non noble metal	aluminium	7429-90-5	0.139	0.04	0.04	418	418
encapsulation	organic material	carbon black	1333-86-4	1.174	0.35		3523	
	plastics	epoxy resin	-	16.439	4.93		49329	
	inorganic material	silicondioxide	60676-86-0	129.167	38.76	44.04	387585	440437
leadfinish	non noble metal	tin	7440-31-5	3.740	1.12	1.12	11223	11223
plating	non noble metal	nickel	7440-02-0	0.523	0.16	0.16	1571	1571
solder	non noble metal	tin	7440-31-5	0.030	0.01		89	
	noble metal	silver	7440-22-4	0.037	0.01		111	
	non noble metal	lead	7439-92-1	1.419	0.43	0.45	4257	4457
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		17	
	non noble metal	iron	7439-89-6	0.019	0.01		58	
	non noble metal	copper	7440-50-8	19.177	5.75	5.76	57545	57620
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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